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(54) Title: SEMICONDUCTOR PROCESS DEVICE

(54) 发明名称: 半导体工艺设备

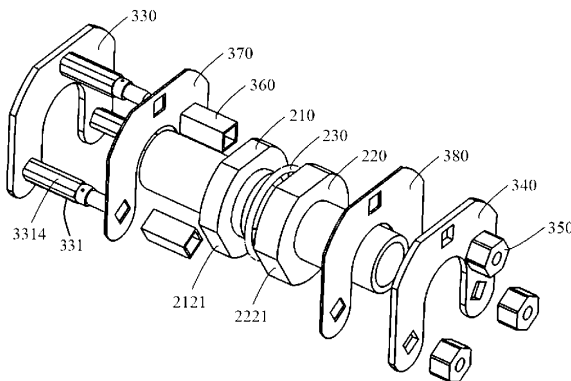


图 3

(57) **Abstract:** A semiconductor process device, comprising a process chamber (100), a first connector (210), a second connector (220), and a connecting apparatus (300), wherein the first connector (210) is connected to the process chamber (100), and the connecting apparatus (300) comprises a first clamping member (330), a second clamping member (340), and a connecting assembly (350); the first clamping member (330) is sleeved on the first connector (210), the second clamping member (340) is sleeved on the second connector (220), one of the first clamping member (330) and the second clamping members (340) is provided with positioning columns (331), and the other is provided with positioning holes (341); the positioning columns (331) are in positioning fit with the positioning holes (341), so that the central axis of the first connector (210) coincides with the central axis of the second connector (220), and a gap is formed between the first connector (210) and the second connector (220); and one end of each positioning column (331) passes through the corresponding positioning hole (341) to be connected to the connecting assembly (350), so as to clamp the first connector (210) and the second connector (220). The problem of air conveying pipelines of existing semiconductor process devices being prone to collision

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本国际公布:
— 包括国际检索报告(条约第21条(3))。
in the butt joint process can be solved.

(57) 摘要: 一种半导体工艺设备, 包括工艺腔室(100)、第一接头(210)、第二接头(220)和连接装置(300), 第一接头(210)与工艺腔室(100)相连, 连接装置(300)包括第一夹持件(330)、第二夹持件(340)和连接组件(350), 第一夹持件(330)套设于第一接头(210), 第二夹持件(340)套设于第二接头(220), 第一夹持件(330)和第二夹持件(340)中的一者具有定位柱(331), 另一者设有定位孔(341), 定位柱(331)与定位孔(341)定位配合, 以使第一接头(210)的中心轴线与第二接头(220)的中心轴线重合, 且第一接头(210)与第二接头(220)之间具有间隙, 定位柱(331)的一端穿过定位孔(341)与连接组件(350)连接, 以夹持第一接头(210)和第二接头(220)。能够解决目前半导体工艺设备的输气管路在对接过程中容易发生碰触的问题。